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	Product Type	:	ST - 3	08			
	Model	:	32.76	8KHz			
	Description	:	DIP/3	808/32.768K	Hz/12.	5pF/20ppm	
	SKC P/N	:	CCHA32768K022				
	SPEC No.	:	1 – 161021 – CCHA32768K022				
			DATE		:	21-Oct-1	6
			Desigr	ner	:	Sound	jue
			Check	ked By	:	Tom	
			Appro	ved By	:	Sam	
		RE	VISION	N HISTC	RY		
Rev	Revise Page	Revise (Contents	Date	R	ef. No.	Reviser
А	N/A	Initial F	Release	21-Oct-16		N/A	Aaron Lee



	ELECTRICAL CHARACTERISTICS				
1	Holder type		ST - 308		
2	Oscillation mode		Fundamental 🗌 3rd Overtone 🗌 5th Overtone		
3	Crystal cutting type		DT CUT		
4	Nominal frequency	FL	32.768KHz		
5	Frequency stability	Tol	±20 ppm (ref at 25 $^\circ\!\!{ m C}$)		
6	Operating temperature range	Topr	-20°C to +70°C		
7	Storage temperature range		-40° C to $+85^{\circ}$ C		
8	Load capacitance	CL	12.5 PF ± 0.2PF		
9	Equivalent series resistance	ESR	30 KOhms max.		
10	Drive level	DL	ι υw max		
11	Shunt capacitance	C0	1.75 pF TYP		
12	Motional capacitance	Cı	3.5 fF TYP		
13	Insulation resistance		500M Ohms min. at DC 100V ± 10V		
14	Aging rate per year		Less than ±5ppm / year		





	RELIABILITY TEST				
We evaluate environmental and mechanical characteristics by the following test condition.					
Measurement will be carried out after letting it alone in the room temperature for 1 to 2 hours.					
	TEST ITEM	TEST METHODS	CRITERIA		
1	Shock 3 Times free drop from 75cm height to hard woo		\triangle F/F \leq ±10 ppm		
		board of thickness more than 30mm.	$ riangle CI \ \leq 5K \ \Omega$		
2	Vibration	Vibration Frequency : 10 to 55Hz			
		Vibration Amplitude : 1.5mm			
	l	Cycle Time:1-2min(10-55-10Hz)	\triangle F/F $\leq \pm$ 10 ppm \triangle CL \leq 5K Q		
	l	Direction : X.Y.Z			
		Duration : 2h/each direction			
3	Resistance to	Put the leads of crystal units into solder melted tank	\triangle F/F $\leq \pm 10 \text{ ppm}$		
	soldering heat	for 5 sec. Temperature : 350° C ±10°C	$ riangle CI \ \leq 10K \ \Omega$		
4	High Temperature	Temperature : $85 \pm 5^{\circ}C$	$\triangle F/F \leq \pm 10 \text{ ppm}$		
	Exposure	Length of Test : 96 ± 4 Hrs	$ riangle CI \ \leq 5K \ \Omega$		
5	Low Temperature	Temperature : -20 \pm 5°C	\triangle F/F $\leq \pm 10$ ppm		
	Exposure	Length of Test : 96 ± 4 Hrs	$ riangle CI \ \leq 5K \ \Omega$		
6	Humidity	Temperature : $40 \pm 2^{\circ}C$			
		Relative Humidity : 90% - 95%	\triangle F/F $\leq \pm$ 10 ppm \triangle CL \leq 5K Q		
		Length of Test : 96 ± 4 Hrs			
7	Temperature Cycle	Cycle : 5 cycles	$\triangle F/F \leq \pm 10 \text{ ppm}$		
		Temp. : 100° C for 30 mins, -40°C for 30 mins.	$ riangle CI \ \leq 5K \ \Omega$		
8	Sealing	Less than 0.5 - 0.6 Mpa, and keep it for 1 hour.	1x10 ⁻⁸ mbar • 1 / s Max		
9	Pulling Test	The crystal lead with the 0.9kg power	No peeling - off		
		keep it for 30s±5s.	at a solder part		
10	Bending Test	bend the crystal lead 90° with 0.45kg power 2 times	No peeling - off		
	1	(bend should be more than 1.5mm from the case)	at a solder part		

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CRYSTAL UNITS SPECIFICATION

Notice

The following instructions and information are provided for the purpose of having the user understand the proper way to process our crystal products to prevent problems prior to use and enhance the reliability of the equipment to which they are applied.

1	When dropped by	The crystal units are designed and manufactured to resist physical shocks.			
	mistake	However, when the crystal units are subjected to excessive impact such			
		as being dropped onto the floor or giving shocks during processing,			
		need to make sure its satisfactory performance before using it.			
2	Soldering	ng A. Lead wires should be soldered within 3 seconds with the soldering iron			
		heated to a temperature no higher than $350^\circ C$.			
		B. In solder-dip processing, the leads should be soldered within 6 seconds with			
		a temperature no higher than 270 $^\circ\!\mathrm{C}$. Mounting in upright is recommendable			
		to prevent the heat conduction directly to the body of the crystal unit.			
3	To bend the lead	A. When the lead of cylinder type crystal units need to be bent, leave more			
		than 1.5mm (3.0mm is recommendable) of lead from the case in order to			
		prevent from any cracks of the hermetic sealing glass at the root of the			
		lead, and use a jig to bend if possible.			
		B. When bending the lead of cylinder type crystal units, do not scrape off the			
		soldering plating from the lead surface.			
4	Mounting				
	A. Soldering the body of the cylinder type crystal units with PCB must be avoided due to deteriorate the				
	characteristics or damage the products. Rubber adhesive is recommended. Rubber adhesive Quartz crystal unit Rubber adhesive Quartz crystal unit				
	Insulator F	CB Insulator PCB PCB			
	B. When the lead needs to be bent by hand, please follow the instruction as below:				
	Hold the body of the	old the body of the cylinder type crystal unit in fingers; pick at the part with tweezers, which you			
	want to bend. There s	hould be more than 1.5mm(3.0mm is recommended) from the body case; Bend			
	the lead 90° by tweez	ers without pulling the lead strongly. If pulling the lead strongly may cause any			
	cracks of hermetic se	racks of hermetic sealing glass at the root of the lead and may cause the leakage and			
	the characteristics to deteriorate.				

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5	Cleaning	A. Crystal units may be affected and destroyed at worst by supersonic
		cleaning or supersonic welding. Please be sure to check if your cleaning
		and welding process affects any damage to crystal units before using.
		B. Some kinds of cleaning fluid may cause any damage to crystal units.
		Please be sure to check suitability of the cleaning fluid in advance.
6	Storage	Storage of crystal units under higher temperature or high humidity for a long
		term may affects frequency stability or solder ability.
		Please store the crystal units under the normal temperature and humidity
		without exposing to direct sunlight and dew condensation, and avoid the
		storage of crystal units for more than 6 months, and mount them as soon as
		possible after unpacking.